

## DM74ALS138

### 3 to 8 Line Decoder/Demultiplexer

#### General Description

These Schottky-clamped circuits are designed to be used in high-performance memory-decoding or data-routing applications, requiring very short propagation delay times. In high-performance memory systems these decoders can be used to minimize the effects of system decoding. When used with high-speed memories, the delay times of these decoders are usually less than the typical access time of the memory. This means that the effective system delay introduced by the decoder is negligible.

The DM74ALS138 decodes one-of-eight lines, based upon the conditions at the three binary select inputs and the three enable inputs. Two active-LOW and one active-HIGH enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented with no external inverters, and 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications.

This decoder/demultiplexer features fully buffered inputs, presenting only one normalized load to its driving circuit. All inputs are clamped with high-performance Schottky diodes to suppress line-ringing and simplify system design.

#### Features

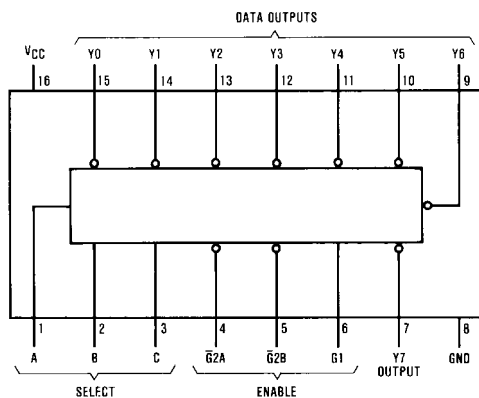
- Designed specifically for high speed:
  - Memory decoders
  - Data transmission systems
- 3- to 8-line decoder incorporates 3 enable inputs to simplify cascading and/or data reception
- Low power dissipation...23 mW typ
- Switching specifications guaranteed over full temperature and  $V_{CC}$  range
- Advanced oxide-isolated, ion-implanted Schottky TTL process

#### Ordering Code:

Order Number	Package Number	Package Description
DM74ALS138M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow
DM74ALS138SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
DM74ALS138N	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

#### Connection Diagram

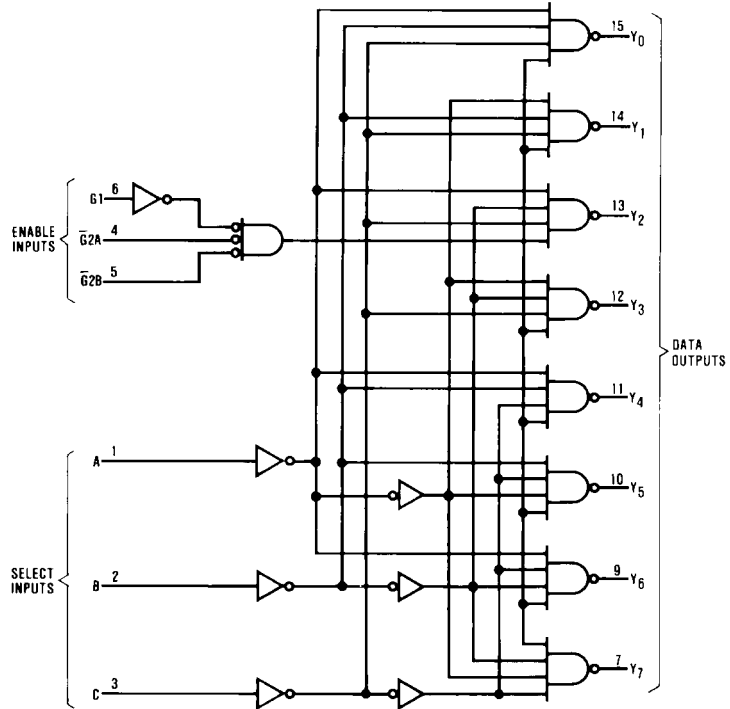


#### Function Table

Enable Inputs		Select Inputs			Outputs							
G1	G2 (Note 1)	C	B	A	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
X	H	X	X	X	H	H	H	H	H	H	H	H
L	X	X	X	X	H	H	H	H	H	H	H	H
H	L	L	L	L	L	H	H	H	H	H	H	H
H	L	L	L	H	H	L	H	H	H	H	H	H
H	L	L	H	L	H	H	L	H	H	H	H	H
H	L	L	H	H	H	H	H	L	H	H	H	H
H	L	H	L	L	H	H	H	H	L	H	H	H
H	L	H	H	L	H	H	H	H	H	L	H	H
H	L	H	H	H	H	H	H	H	H	H	L	H
H	L	H	H	H	H	H	H	H	H	H	H	L

Note 1:  $\overline{G2} = \overline{G2A} + \overline{G2B}$

### Logic Diagram



**Absolute Maximum Ratings**(Note 2)

Supply Voltage	7V
Input Voltage	7V
Operating Free Air Temperature Range	0°C to +70°C
Storage Temperature Range	-65°C to +150°C
Typical $\theta_{JA}$	
N Package	75.5°C/W
M Package	104.0°C/W

**Note 2:** The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

**Recommended Operating Conditions**

Symbol	Parameter	Min	Nom	Max	Units
$V_{CC}$	Supply Voltage	4.5	5	5.5	V
$V_{IH}$	HIGH Level Input Voltage	2			V
$V_{IL}$	LOW Level Input Voltage			0.8	V
$I_{OH}$	HIGH Level Output Current			-0.4	mA
$I_{OL}$	LOW Level Output Current			8	mA
$T_A$	Free Air Operating Temperature	0		70	°C

**Electrical Characteristics**

over recommended operating free air temperature range. All typical values are measured at  $V_{CC} = 5V$ ,  $T_A = 25^\circ C$ .

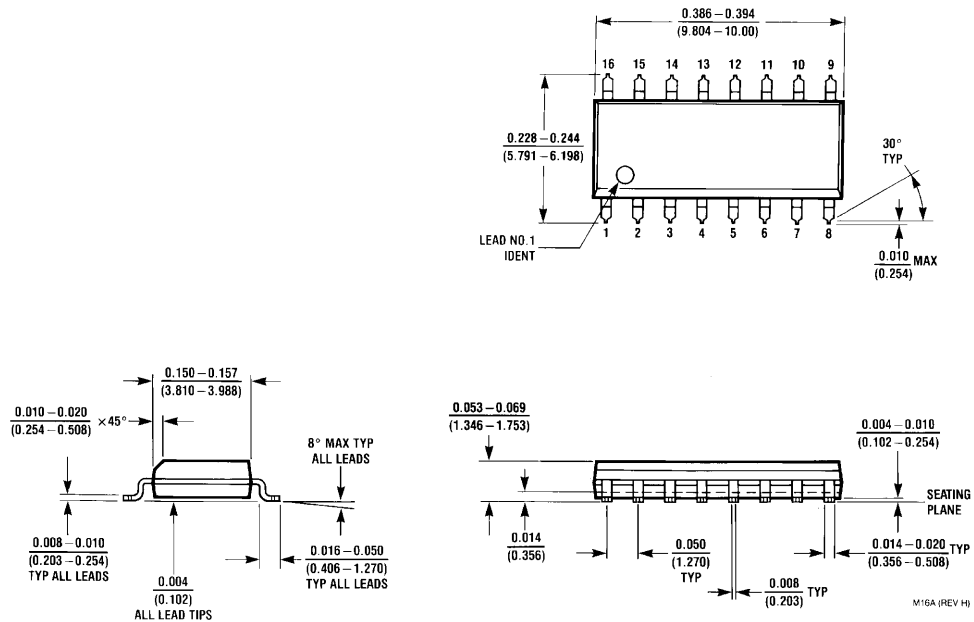
Symbol	Parameter	Conditions	Min	Typ	Max	Units
$V_{IK}$	Input Clamp Voltage	$V_{CC} = 4.5V$ , $I_I = -18\text{ mA}$			-1.5	V
$V_{OH}$	HIGH Level Output Voltage	$I_{OH} = -0.4\text{ mA}$ $V_{CC} = 4.5V\text{ to }5.5V$	$V_{CC} - 2$			V
$V_{OL}$	LOW Level Output Voltage	$V_{CC} = 4.5V$ , $I_{OL} = 8\text{ mA}$		0.35	0.5	V
$I_I$	Input Current @ Max. Input Voltage	$V_{CC} = 5.5V$ , $V_{IH} = 7V$			0.1	mA
$I_{IH}$	HIGH Level Input Current	$V_{CC} = 5.5V$ , $V_{IH} = 2.7V$			20	$\mu A$
$I_{IL}$	LOW Level Input Current	$V_{CC} = 5.5V$ , $V_{IL} = 0.4V$			-0.1	mA
$I_O$	Output Drive Current	$V_{CC} = 5.5V$ , $V_O = 2.25V$	-30		-112	mA
$I_{CC}$	Supply Current	$V_{CC} = 5.5V$		5	10	mA

**Switching Characteristics**

over recommended operating free air temperature range.

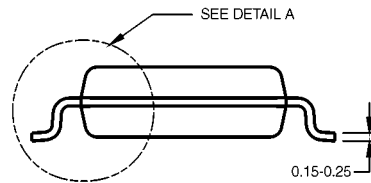
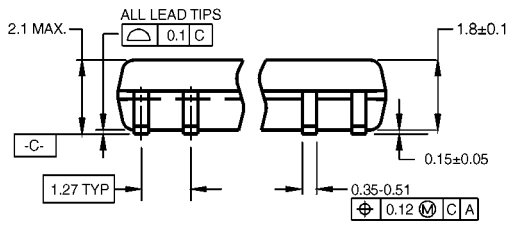
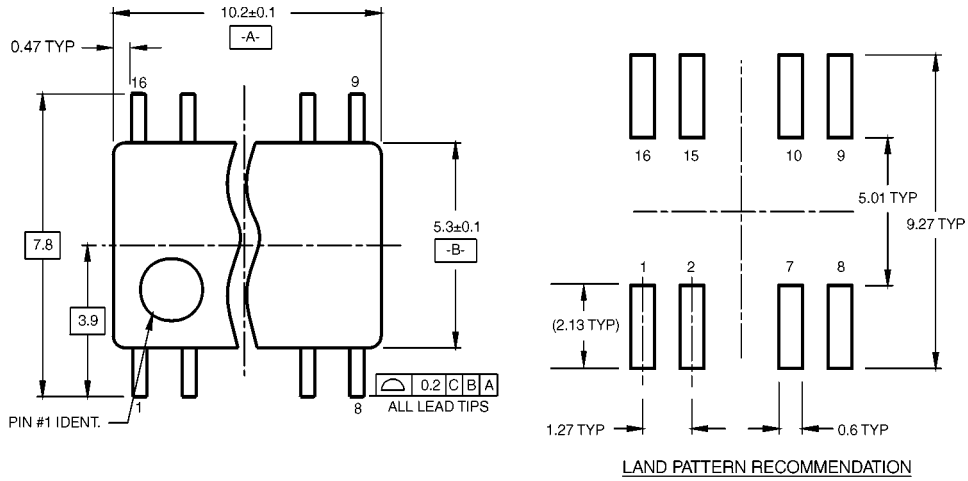
Symbol	Parameter	Conditions	From (Input) To (Output)	Min	Max	Units
$t_{PLH}$	Propagation Delay Time LOW-to-HIGH Level Output	$V_{CC} = 4.5V\text{ to }5.5V$ $R_L = 500\Omega$ $C_L = 50\text{ pF}$	A, B, C to Y	6	22	ns
$t_{PHL}$	Propagation Delay Time HIGH-to-LOW Level Output		A, B, C to Y	6	18	ns
$t_{PLH}$	Propagation Delay Time LOW-to-HIGH Level Output		Enable to Y	4	17	ns
$t_{PHL}$	Propagation Delay Time HIGH-to-LOW Level Output		Enable to Y	5	17	ns

**Physical Dimensions** inches (millimeters) unless otherwise noted



**16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow  
Package Number M16A**

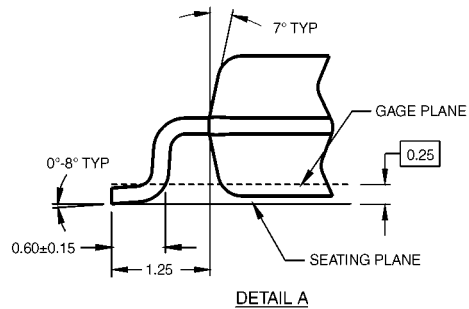
**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

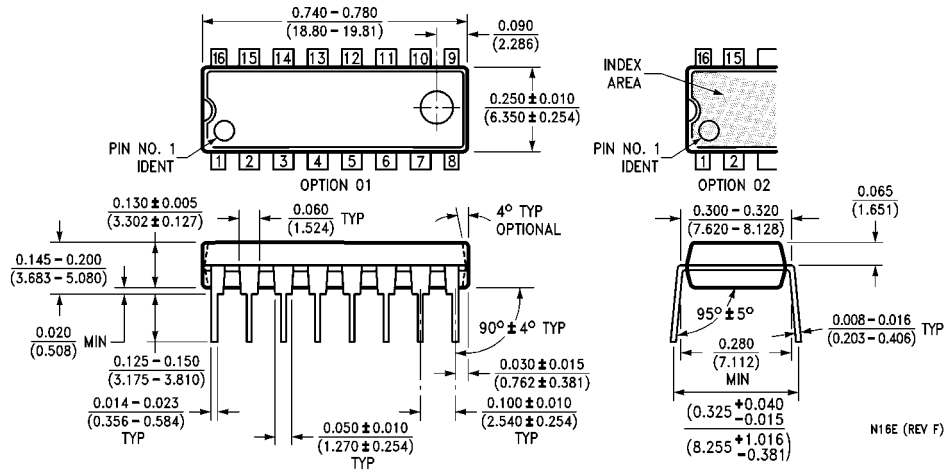
- NOTES:  
 A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.  
 B. DIMENSIONS ARE IN MILLIMETERS.  
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M16DRevB1



**16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide  
 Package Number M16D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N16E**

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